

ISSUE CLASSIFICATION	
Class	Subclass

FILED UNDER 35 U.S.C. 371

PATENT NUMBER

U.S. UTILITY Patent Application

O.I.P.E. <i>mk</i> SCANNED <i>TR</i> Q.A. <i>Am</i>	PATENT DATE
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APPLICATION NO. 09/980040	CONT/PRIOR D	CLASS 361 439	SUBCLASS G9	ART UNIT 2841 2839	EXAMINER Ducorne
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APPLICANTS

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THE

Construction structures and manufacturing processes for integrated circuit wafer probe card assemblies

PTO-2040
12/89[illegible]

<input type="checkbox"/> TERMINAL DISCLAIMER	DRAWINGS			CLAIMS ALLOWED	
	Sheets Drwg.	Figs. Drwg.	Print Fig.	Total Claims	Print Claim for O.G.
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